PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chih-Wei Hsu	03/18/2010
Jin-Ning Sung	03/18/2010
Shin-Rung Lu	03/25/2010
Jong-I Mou	03/25/2010

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12731348

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 214-651-5000

Email: ipdocketing@haynesboone.com
Correspondent Name: HAYNES AND BOONE, LLP

Address Line 1: 2323 Victory Avenue

Address Line 2: Suite 700

Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.1412
NAME OF SUBMITTER:	David M. O'Dell

Total Attachments: 3

PATENT REEL: 024135 FRAME: 0913 1 \$40.00 12/3134

501129697

source=1412_Assignment#page1.tif source=1412_Assignment#page2.tif source=1412_Assignment#page3.tif

> PATENT REEL: 024135 FRAME: 0914

Docket No.: 2009-0721 / 24061,1412

Customer No.: 42717

ASSIGNMENT

WHEREAS, we, **(1)** Chih-Wei Hsu of No. 8, Huei-Ming Juang Chuang-Hua City, Taiwan, R.O.C. **(2)** Jin-Ning Sung ofNo. 10, Alley 4, Lane 183, Kaifong Street Pingihen City, Taoyuan County 324, Taiwan, R.O.C. (3) Shin-Rung Lu of 8F, No. 185, Wen-Yi Street Chu-Pei City, Hsin-Chu County, Taiwan, R.O.C. (4) Jong-I Mou of No. 11, Daxiang Road Hsinpu Township, Hsinchu County 30542, Taiwan,

have invented certain improvements in

R.O.C.

DYNAMIC COMPENSATION IN ADVANCED PROCESS CONTROL

for which we have executed an application for Letters Patent of the United States of America,

	of even date filed herewith; and	
Х	filed on March 25, 2010 and	
	assigned application no. 12/731.348	and:

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal; substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Page 1 of 3

R-1412 (2009-0721) - Assignment

Docket No.: 2009-0721 / 24061.1412

Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Chih-Wei Hsu

Residence Address:

No. 8, Huei-Ming Juang

Chuang-Hua City, Taiwan, R.O.C.

Dated: Mar. 18, 2010

Inventor Signature

C

Inventor Name:

Jin-Ning Sung

Residence Address:

R-1412 (2009-0721) - Assignment

No. 10, Alley 4, Lane 183, Kaifong Street

Pingihen City, Taoyuan County 324, Taiwan, R.O.C.

Dated: Mar. 18. 2010

Sung Jin - Wing
Inventor Signature

Page 2 of 3

Docket No.: 2009-0721 / 24061.1412

Customer No.: 42717

Inventor Name:

Shin-Rung Lu

Residence Address:

8F, No. 185, Wen-Yi Street

Chu-Pei City, Hsin-Chu County, Taiwan, R.O.C.

Dated: $\frac{3}{2} / \frac{1}{2} / \frac{3}{2} = \frac{3}{2}$

Shin Rung Lw Inventor Signature

Inventor Name:

Jong-I Mou

Residence Address:

No. 11, Daxiang Road

Hsinpu Township, Hsinchu County 30542, Taiwan, R.O.C.

Dated: 3/25/010

Inventor Signature

R-1412 (2009-0721) - Assignment

RECORDED: 03/25/2010

Page 3 of 3

PATENT REEL: 024135 FRAME: 0917